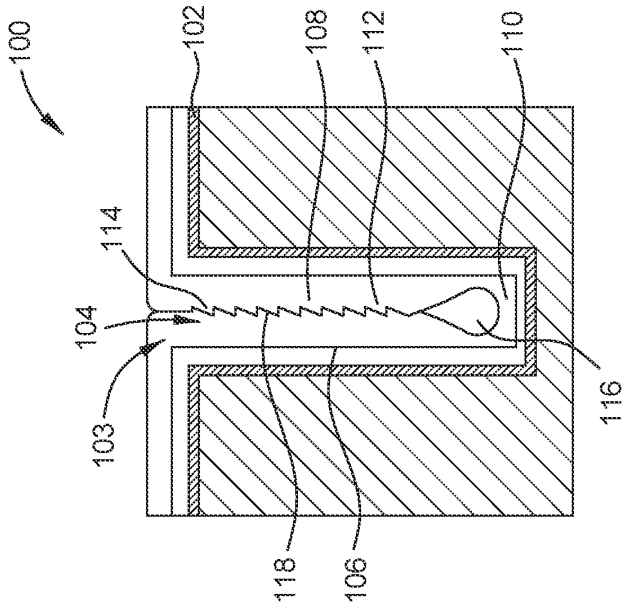

100
102
108
112
110
114
104
103
116
118
106

FIG. 1B

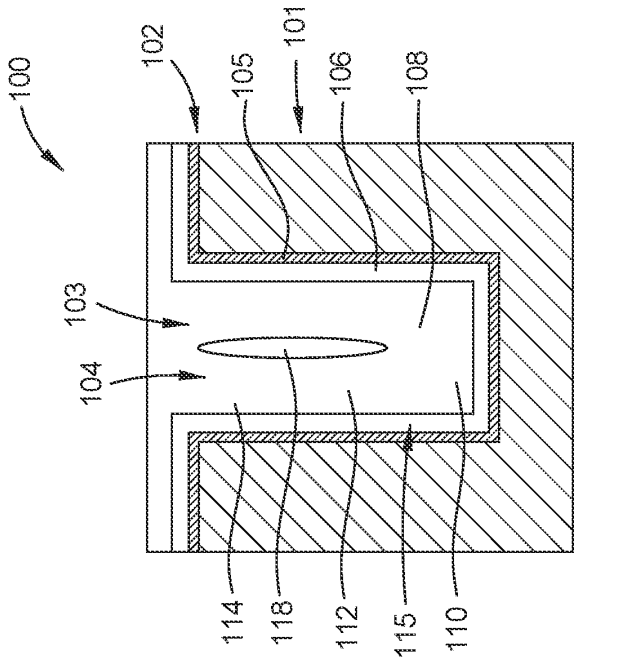

100
102
105
101
106
108
103
104
114
118
112
115
110

FIG. 1A

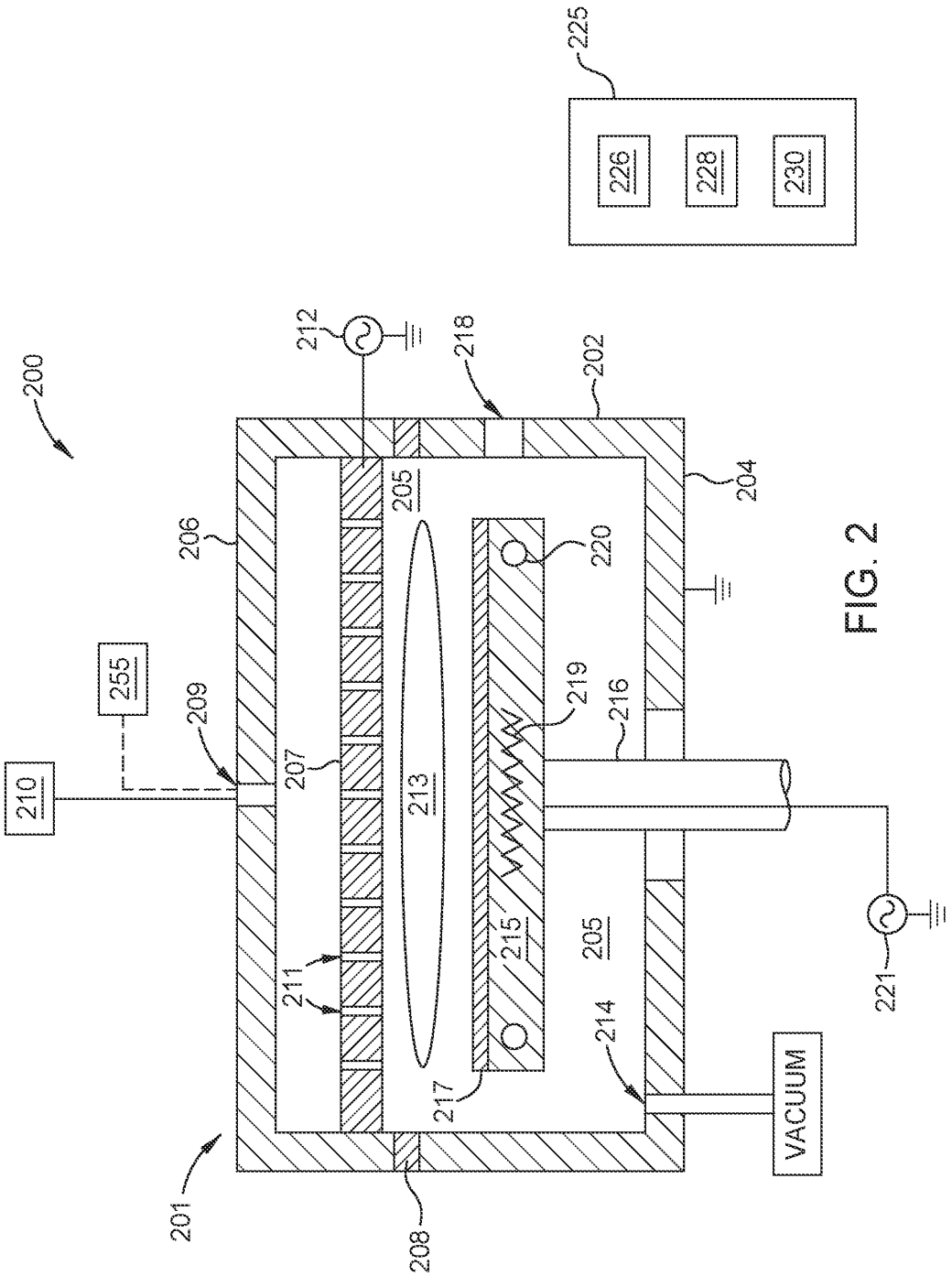

225
226
228
230
200
212
218
202
204
205
206
220
255
209
219
216
210
207
213
205
215
211
214
217
VACUUM
221
201
208

FIG. 2

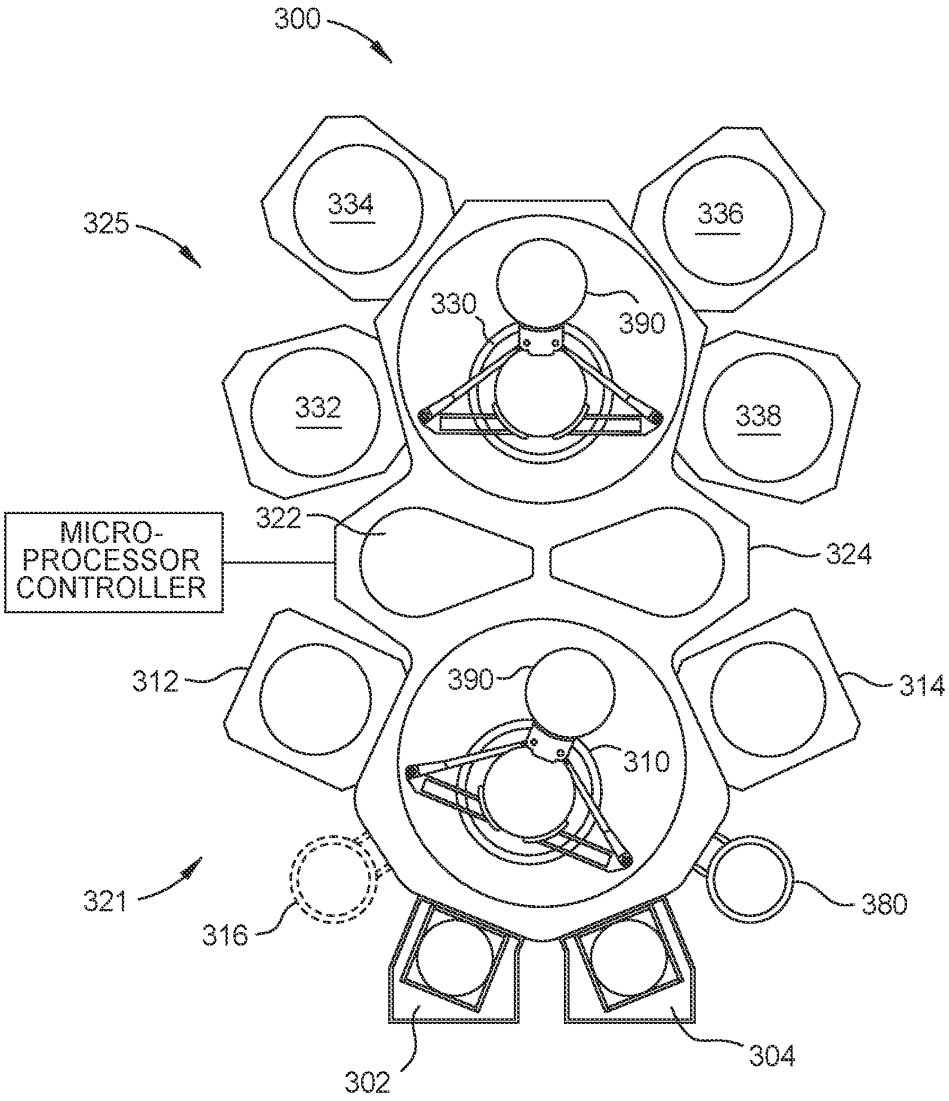

300
325
334
336
330
390
332
338
MICRO-
PROCESSOR
CONTROLLER
322
324
312
390
314
310
321
316
380
302
304

FIG. 3

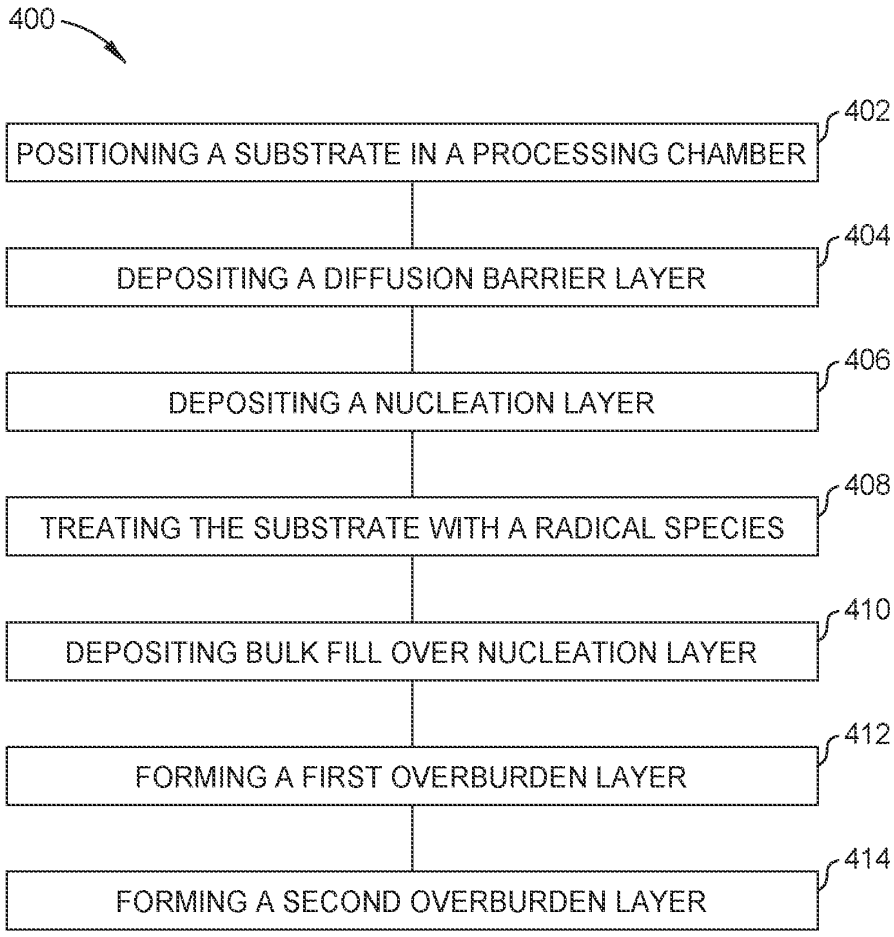

400
POSITIONING A SUBSTRATE IN A PROCESSING CHAMBER
402
DEPOSITING A DIFFUSION BARRIER LAYER
404
DEPOSITING A NUCLEATION LAYER
406
TREATING THE SUBSTRATE WITH A RADICAL SPECIES
408
DEPOSITING BULK FILL OVER NUCLEATION LAYER
410
FORMING A FIRST OVERBURDEN LAYER
412
FORMING A SECOND OVERBURDEN LAYER
414

FIG. 4

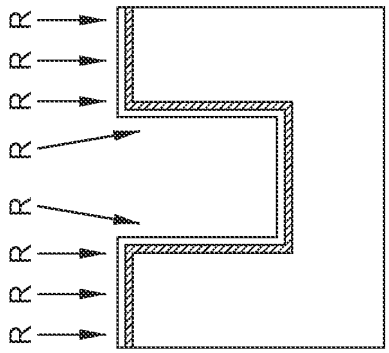


FIG. 5C

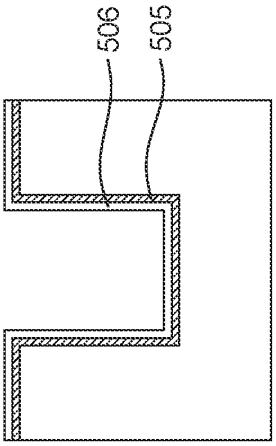


FIG. 5B

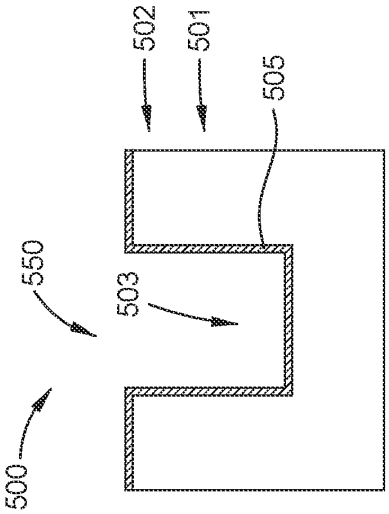


FIG. 5A

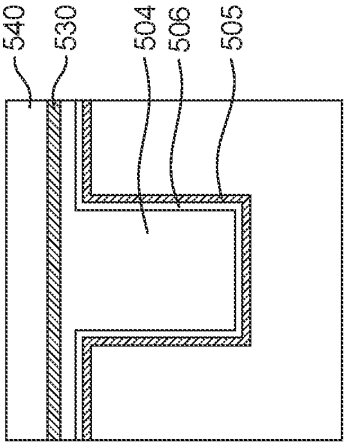


FIG. 5E

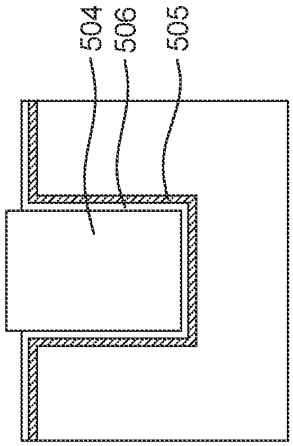


FIG. 5D

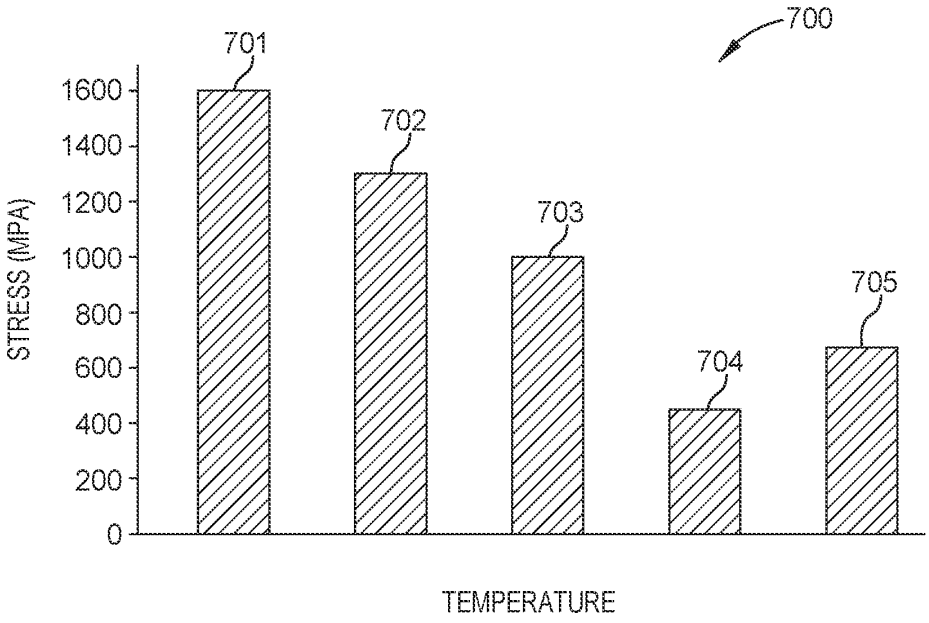

700
701
702
703
704
705
1600
1400
1200
1000
800
600
400
200
0
STRESS (MPA)
TEMPERATURE

FIG. 6